(\$.	
-	3643	((thermal heat) near3 (sens\$4 measur\$4 test identif\$4	USPAT;	2003/09/26 10:35
		detect\$4 determin\$4 monitor\$4 comput\$4 calculat\$4	US-PGPUB;	
		indicat\$4 evaluat\$4 estimat\$4 transducer gauge) near3 gas)	EPO; JPO;	
		and (gap groove dip recess\$4 space opening hole crack)	DERWENT;	
	_		IBM_TDB	
-	0	(((thermal heat) near3 (sens\$4 measur\$4 test identif\$4	USPAT;	2003/09/26 10:31
		detect\$4 determin\$4 monitor\$4 comput\$4 calculat\$4	US-PGPUB;	
		indicat\$4 evaluat\$4 estimat\$4 transducer gauge) near3 gas)	EPO; JPO;	
		and (gap groove dip recess\$4 space opening hole crack))	DERWENT;	,
		and (wafer\$4 layer\$4 substrate\$4 disk\$4 film\$4) same	IBM_TDB	
1	1	stiction (((thermal heat) near3 (sens\$4 measur\$4 test identif\$4	USPAT;	2003/09/26 10:31
-	•	detect\$4 determin\$4 monitor\$4 comput\$4 calculat\$4	US-PGPUB;	2003/09/20 10.31
		indicat\$4 evaluat\$4 estimat\$4 transducer gauge) near3 gas)	EPO; JPO;	
		and (gap groove dip recess\$4 space opening hole crack))	DERWENT;	
		and stiction	IBM_TDB	
_	o	(((thermal heat) near3 (sens\$4 measur\$4 test identif\$4	USPAT;	2003/09/26 10:34
		detect\$4 determin\$4 monitor\$4 comput\$4 calculat\$4	US-PGPUB;	
		indicat\$4 evaluat\$4 estimat\$4 transducer gauge) near3 gas)	EPO; JPO;	,
		and (gap groove dip recess\$4 space opening hole crack))	DERWENT:	
-	*	and (wafer\$4 layer\$4 substrate\$4 disk\$4 film\$4) near3	IBM_TDB	:
		stiction	_	
-	1964	(((thermal heat) near3 (sens\$4 measur\$4 test identif\$4	USPAT;	2003/09/26 10:35
		detect\$4 determin\$4 monitor\$4 comput\$4 calculat\$4	US-PGPUB;	
		indicat\$4 evaluat\$4 estimat\$4 transducer gauge) near3 gas)	EPO; JPO;	
		and (gap groove dip recess\$4 space opening hole crack))	DERWENT;	
		and (wafer\$4 layer\$4 substrate\$4 disk\$4 film\$4) (bond\$4	IBM_TDB	
	2022	adhere\$4 stick\$4) near3 stiction	USPAT;	2003/09/26-10:35
-	2823	((thermal heat) near3 (sens\$4 measur\$4 test identif\$4 detect\$4 determin\$4 monitor\$4 comput\$4 calculat\$4	US-PGPUB;	2003/09/20:10.33
		indicat\$4 evaluat\$4 estimat\$4 transducer gauge) near3 gas)	EPO; JPO;	
		and (wafer\$4 layer\$4 substrate\$4 disk\$4 film\$4) (bond\$4	DERWENT;	
		adhere\$4 stick\$4) near3 stiction	IBM TDB	
	l o	((thermal heat) near3 (sens\$4 measur\$4 test identif\$4	USPAT;	2003/09/26 10:36
	_	detect\$4 determin\$4 monitor\$4 comput\$4 calculat\$4	US-PGPUB;	
		indicat\$4 evaluat\$4 estimat\$4 transducer gauge) near3 gas)	EPO; JPO;	
		and (wafer\$4 layer\$4 substrate\$4 disk\$4 film\$4) same	DERWENT;	
		(bond\$4 adhere\$4 stick\$4) near3 stiction	IBM_TDB	
-	103	(wafer\$4 layer\$4 substrate\$4 disk\$4 film\$4) same (bond\$4	USPAT;	2003/09/26 10:46
	•	adhere\$4 stick\$4) near3 stiction	US-PGPUB;	
		·	EPO; JPO;	
			DERWENT;	
	10	/ (far@4 lawar@4 auhatrata@4 diak@4 film@4) cama /hand@4	IBM_TDB USPAT;	2003/09/26 10:37
-	10	((wafer\$4 layer\$4 substrate\$4 disk\$4 film\$4) same (bond\$4 adhere\$4 stick\$4) near3 stiction) and(thermal heat) near3	US-PGPUB;	2000/08/20 10.0/
		(sens\$4 measur\$4 test identif\$4 detect\$4 determin\$4	EPO; JPO;	
		monitor\$4 comput\$4 calculat\$4 indicat\$4 evaluat\$4	DERWENT;	
		estimat\$4 transducer gauge)	IBM TDB	
-	10	((wafer\$4 layer\$4 substrate\$4 disk\$4 film\$4) same (bond\$4	USPAT;	2003/09/26 10:43
		adhere\$4 stick\$4) near3 stiction) and (thermal heat) near3	US-PGPUB;	
		(sens\$4 measur\$4 test identif\$4 detect\$4 determin\$4	EPO; JPO;	
		monitor\$4 comput\$4 calculat\$4 indicat\$4 evaluat\$4	DERWENT;	•
		estimat\$4 transducer gauge)	IBM_TDB	
-	2	((wafer\$4 layer\$4 substrate\$4 disk\$4 film\$4) same (bond\$4	USPAT;	2003/09/26 10:42
		adhere\$4 stick\$4) near3 stiction) and (thermal heat) near3	US-PGPUB;	
		(sens\$4 measur\$4 test identif\$4 detect\$4 determin\$4	EPO; JPO;	
		monitor\$4 comput\$4 calculat\$4 indicat\$4 evaluat\$4 estimat\$4 transducer gauge) same gas	DERWENT; IBM_TDB	
	36	((wafer\$4 layer\$4 substrate\$4 disk\$4 film\$4) same (bond\$4	USPAT;	2003/09/26 10:43
_	30	adhere\$4 stick\$4) near3 stiction) and (thermal heat\$4) near3	US-PGPUB:	2000/00/20 10.40
		(sens\$4 measur\$4 test identif\$4 detect\$4 determin\$4	EPO; JPO;	
		monitor\$4 comput\$4 calculat\$4 indicat\$4 evaluat\$4	DERWENT:	
		estimat\$4 transducer gauge)	IBM_TDB	
L	<u> </u>	1	·	

-	11	((wafer\$4 layer\$4 substrate\$4 disk\$4 film\$4) same (bond\$4 adhere\$4 stick\$4) near3 stiction) and (thermal heat\$4) near3 (sens\$4 measur\$4 test identif\$4 detect\$4 determin\$4 monitor\$4 comput\$4 calculat\$4 indicat\$4 evaluat\$4 estimat\$4 transducer gauge) same gas	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/09/26 10:48
-	1708	(wafer\$4 layer\$4 substrate\$4 disk\$4 film\$4) same (bond\$4 adhere\$4 stick\$4) near3 (stiction friction)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/26 10:48
-	15	((wafer\$4 layer\$4 substrate\$4 disk\$4 film\$4) same (bond\$4 adhere\$4 stick\$4) near3 (stiction friction)) and (thermal heat\$4) near3 (sens\$4 measur\$4 test identif\$4 detect\$4 determin\$4 monitor\$4 comput\$4 calculat\$4 indicat\$4 evaluat\$4 estimat\$4 transducer gauge) same gas	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/10/02 15:30
-	1	(wafer\$4 layer\$4 substrate\$4 film\$4) near3 stiction and (thermal heat\$4) near3 (sens\$4 measur\$4 test identif\$4 detect\$4 determin\$4 monitor\$4 comput\$4 calculat\$4 indicat\$4 evaluat\$4 estimat\$4 transducer gauge) near3 temperature	USPAT; EPO; JPO; DERWENT; IBM_TDB	2003/10/02 15:32
-	17		USPAT; EPO; JPO; DERWENT; IBM_TDB	2003/10/02 15:33
-	207	(wafer\$4 layer\$4 substrate\$4 film\$4) near3 stiction	USPAT; EPO; JPO; DERWENT; IBM_TDB	2003/10/02 15:35